## Nch 100V 120A Power MOSFET

V <sub>DSS</sub>	100V
R <sub>DS(on)</sub> (Max.)	5.8mΩ
I <sub>D</sub>	±120A
P <sub>D</sub>	178W

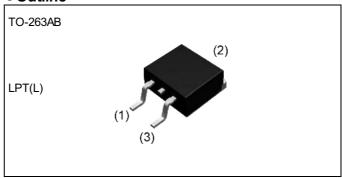
## Features

- 1) Low on resistance
- 2) High power small mold package
- 3) Pb-free lead plating; RoHS compliant
- 4) UIS tested
- 5) Halogen free

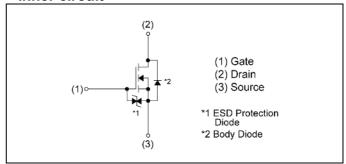
## Application

Switching

## Outline



## •Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Type	Tape width (mm)	24
	Quantity (pcs)	1000
	Taping code	TLL
	Marking	RJ1P12BBD

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V <sub>DSS</sub>	100	V
Continuous drain current	V <sub>GS</sub> = 10V	I <sub>D</sub> *1	±120	Α
Pulsed drain current		I <sub>DP</sub> *2	±240	Α
Gate - Source voltage	V <sub>GSS</sub>	±20	V	
Avalanche current, single pulse		I <sub>AS</sub> *3	40	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	125	mJ	
Power dissipation	P <sub>D</sub> *1	178	W	
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage ter	nperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Parameter	Cymbol	Values			l limit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	0.70	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cymahal	Conditions	Values			Unit	
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	100	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	98.33	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	10	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	-	-	±10	μΑ	
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 2.5mA	2.0	-	4.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-8.28	-	mV/°C	
Static drain - source	D *4	V <sub>GS</sub> = 10V, I <sub>D</sub> = 50A	-	4.4	5.8	m0	
on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 6.0V, I <sub>D</sub> = 40A	-	5.2	7.8	mΩ	
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	2.6	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = 5V, I <sub>D</sub> = 40A	30	-	-	S	

<sup>\*1</sup> T<sub>c</sub> =25°C, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw≦10µs , Duty cycle≦1%

<sup>\*3</sup> L  $\simeq$  0.10mH, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Symbol Conditions		Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Uniii	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	4170	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 50V	-	590	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	130	-		
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq 50V, V_{GS} = 10V$	-	37	-		
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 50A	1	33	1	no	
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 1.0\Omega$	-	125	-	ns	
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	54	-		

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

Darameter	Cymahal	Canditiana		Values			l limit
Parameter	Symbol Condition		Oris	Min.	Тур.	Max.	Unit
Total gate charge	O *4		V <sub>GS</sub> = 10V	-	80.0	-	
Total gate charge	Q <sub>g</sub> *4	V <sub>DD</sub> ≈ 50V		-	51.0	-	<b>~</b> C
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 50A	V <sub>GS</sub> = 6V	-	24.0	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4			-	17.5	-	

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub>	T <sub>a</sub> = 25°C	-	-	120	Α
Pulse forward current	I <sub>SP</sub> *2	1 <sub>a</sub> - 25 C	-	-	240	Α
Forward voltage	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = 40A	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = 50A, V <sub>GS</sub> =0V	-	67	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	di/dt = 100A/μs	-	225	-	nC

Fig.1 Power Dissipation Derating Curve

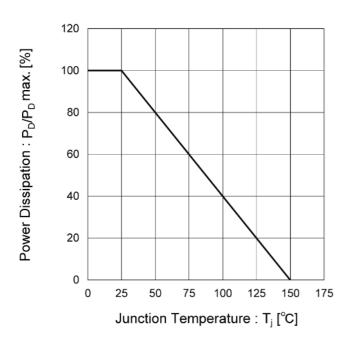


Fig.2 Maximum Safe Operating Area

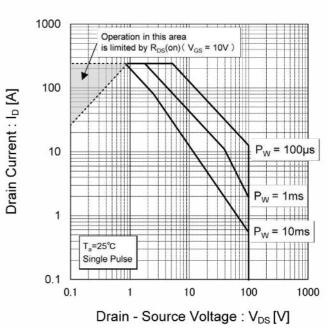


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

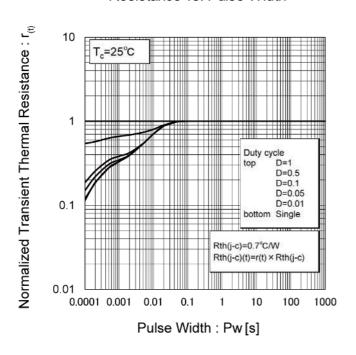


Fig.4 Single Pulse Maximum Power dissipation

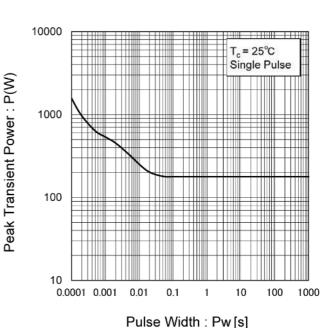
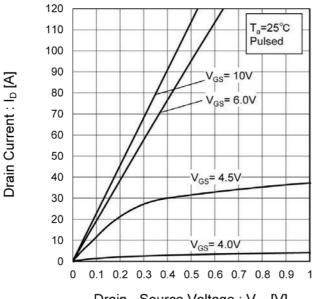
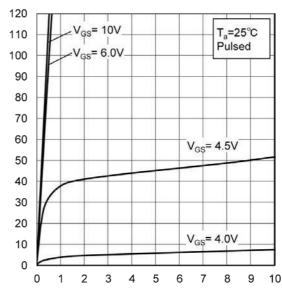


Fig.5 Typical Output Characteristics(I)



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.6 Typical Output Characteristics(II)



Drain Current: Ip [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Breakdown Voltage vs.

Junction Temperature

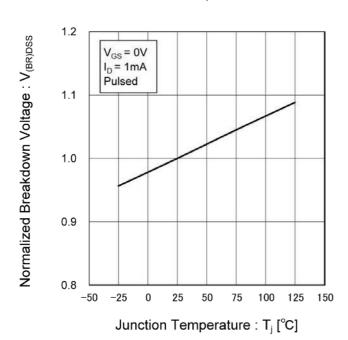


Fig.8 Typical Transfer Characteristics

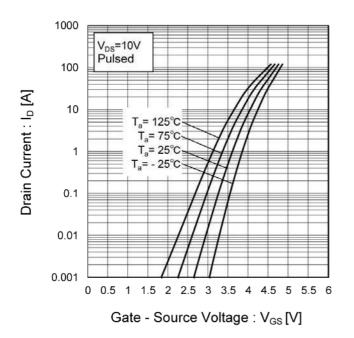


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

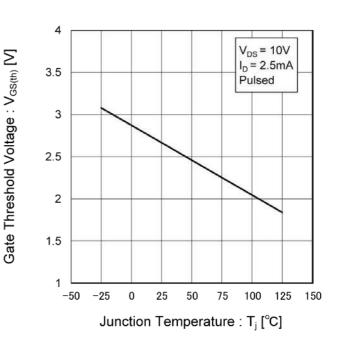


Fig.10 Forward Transfer Admittance vs.
Drain Current

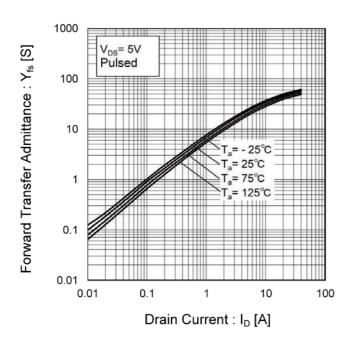


Fig.11 Drain Current Derating Curve

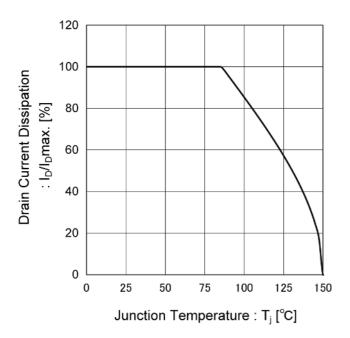


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

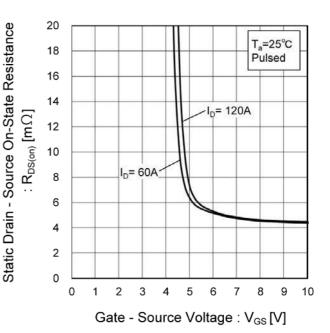


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

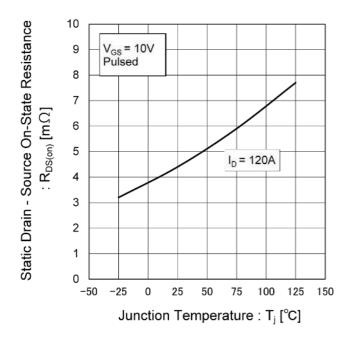


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

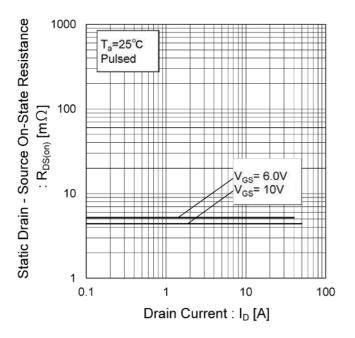


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

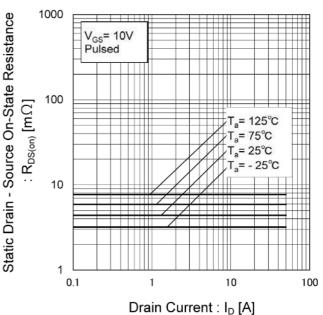
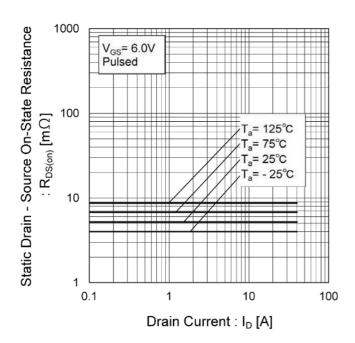


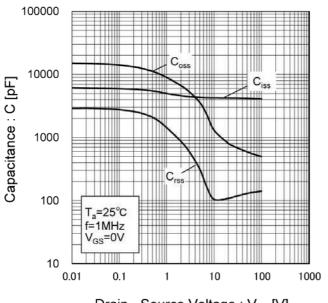
Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)



8/11

Fig.17 Typical Capacitance vs.

Drain - Source Voltage



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.18 Switching Characteristics

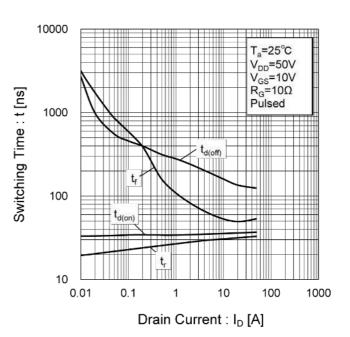


Fig.19 Dynamic Input Characteristics

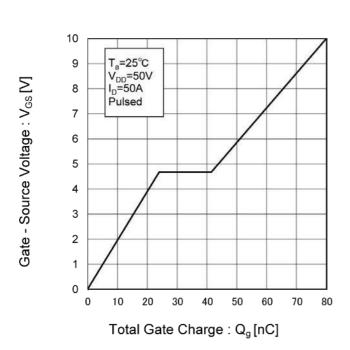
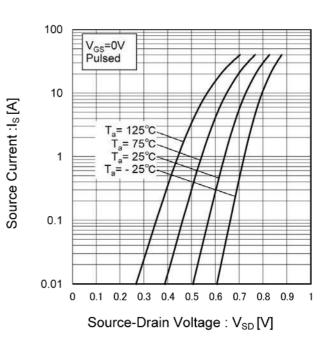


Fig.20 Source Current vs.

Source Drain Voltage



## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

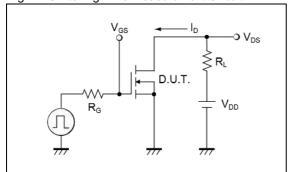


Fig.2-1 Gate Charge Measurement Circuit

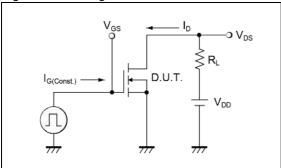


Fig.3-1 Avalanche Measurement Circuit

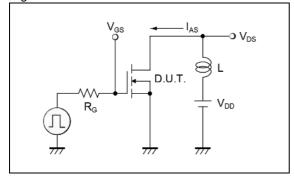


Fig.1-2 Switching Waveforms

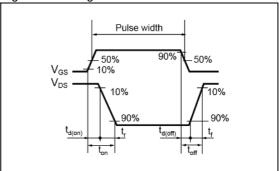


Fig.2-2 Gate Charge Waveform

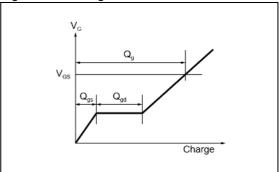
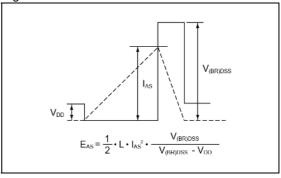
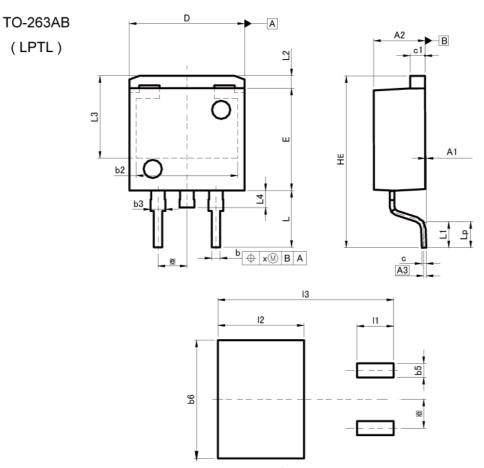


Fig.3-2 Avalanche Waveform



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.9	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1,10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.100	
HE	14.80	15.40	0.583	0.606
L	4.70	5.30	0.185	0.209
L1	2.10	2.70	0.083	0.106
L2	1,	1.10		43
L3	7.25		0.285	
L4	1.	50	0.0	159
Lp	2.60	2.00	0.102	0.079
х	275	0.25	S=0	0.010

DIM	MILIM	ETERS	INCHES	
DIM	DIM MIN M	MAX	MIN	MAX
b5		1.23	=	0.049
b6	94	10.40	<b>=</b>	0.409
11	4	3.20	-	0.126
12	27	7.55	S <del>-1</del>	0.297
13	S <del></del>	15.40	; <del>=</del>	0.606

Dimension in mm/inches



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CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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